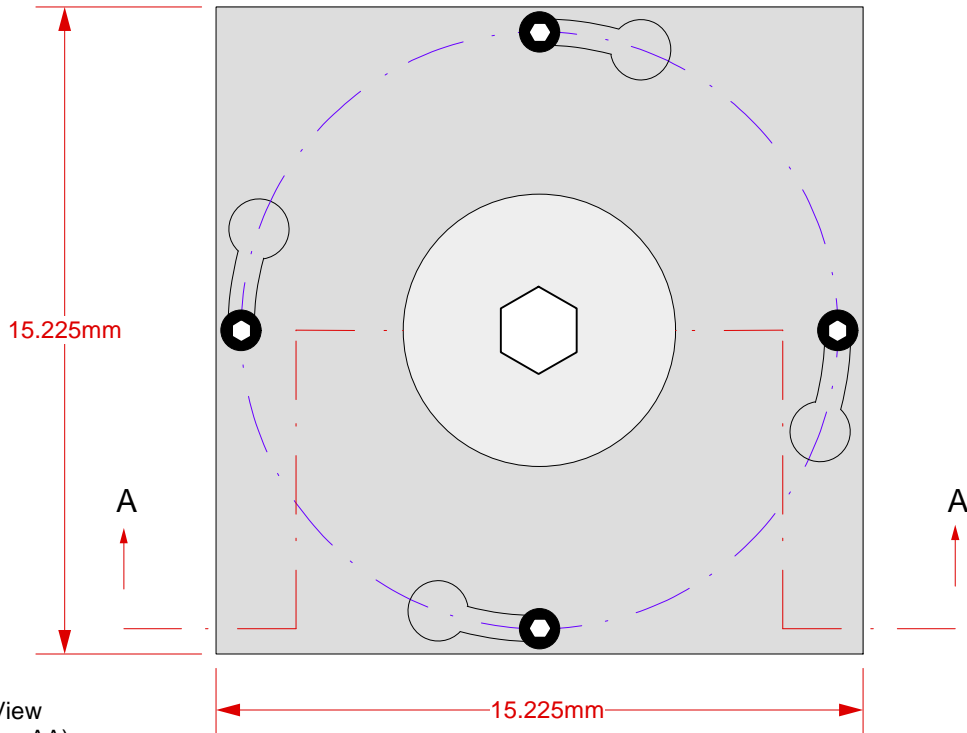


Top View

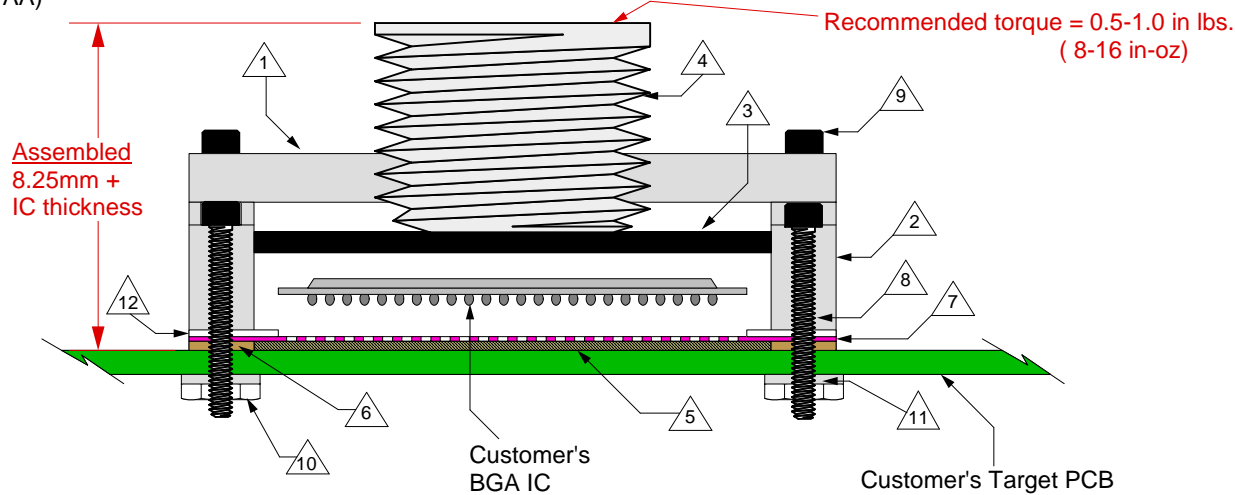


# GHz BGA Socket - Direct mount, solderless

## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View  
(Section AA)



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 3mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, 18-8 Stainless steel, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thick.
- △ 12 IC Guide: 0.5mm thick.

## SG-BGA-6161 Drawing

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PO BOX 21151 ST. PAUL, MN 55121  
Tele: (651) 452-8100  
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: C

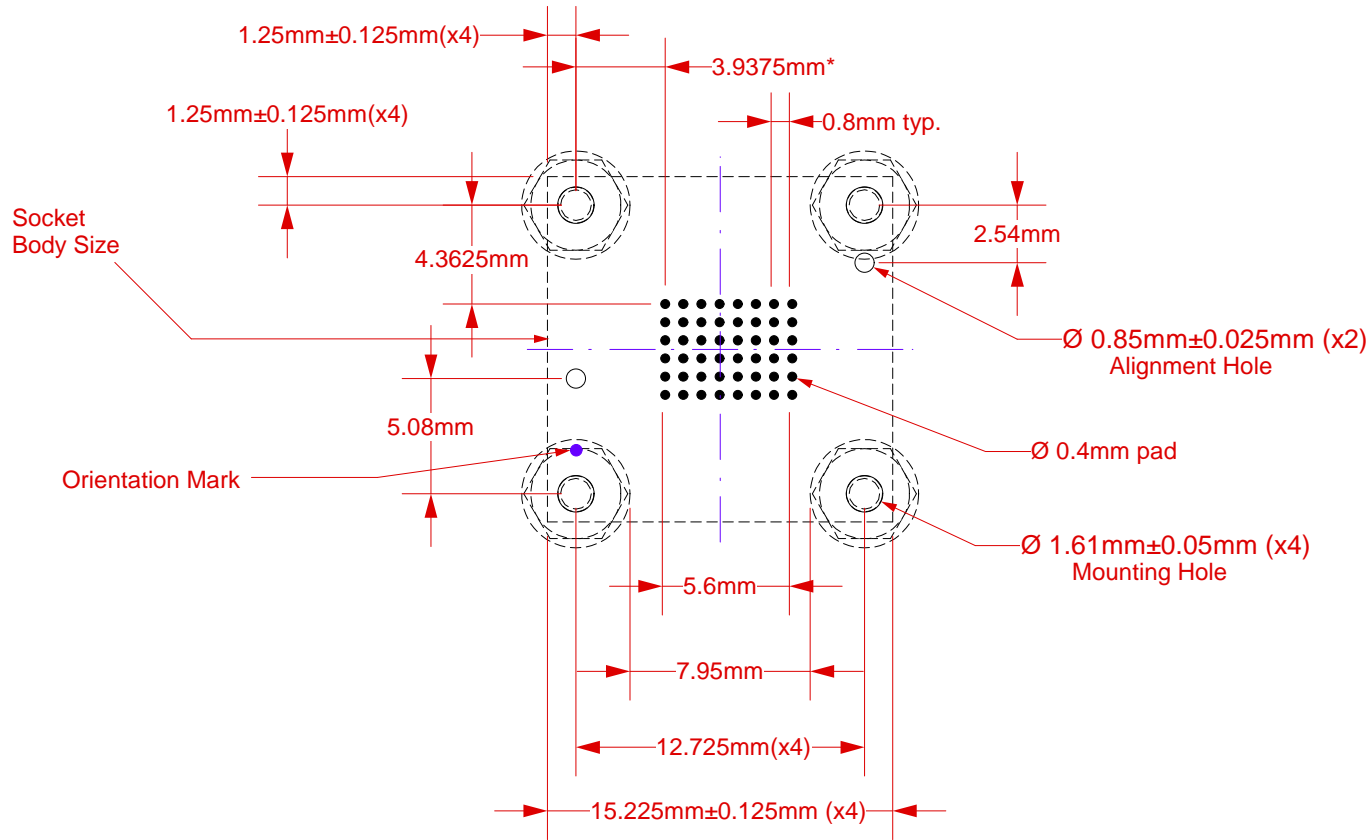
Drawing: S.Natarajan

Date: 10/14/05

File: SG-BGA-6161 Dwg.mcd

Modified: 6/2/09, AE


All tolerances:  $\pm 0.125\text{mm}$  (unless stated otherwise). Materials and specifications are subject to change without notice.

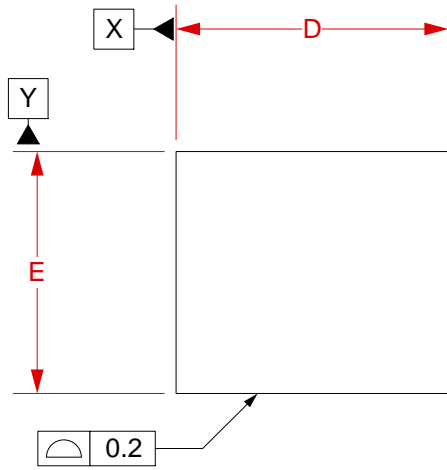


Target PCB Recommendations

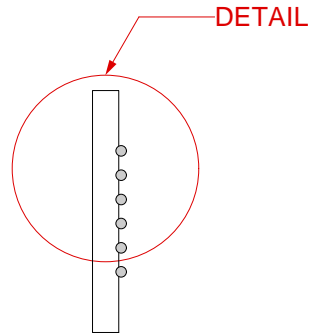
Total thickness: 1.6mm or high  
 Plating: Gold or Solder finish  
 PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001$ "] unless stated otherwise.

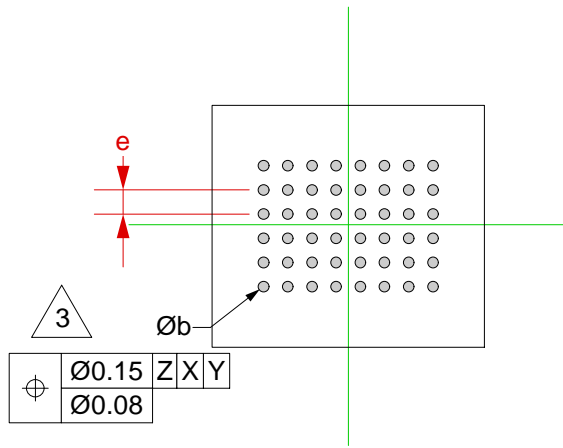
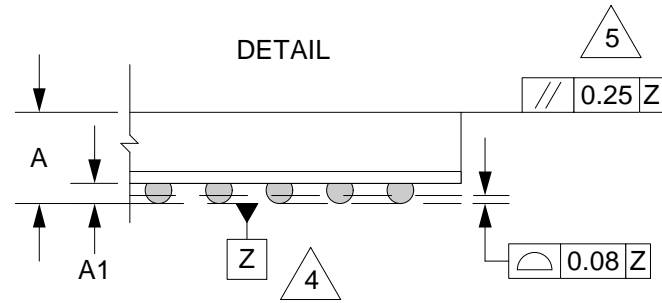
	<b>SG-BGA-6161 Drawing</b>	Status: Released	Scale: 3:1	Rev: C
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		File: SG-BGA-6141 Dwg.mcd	Modified: 06/02/09, AE	



TOP VIEW



SIDE VIEW



BOTTOM VIEW

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.20
A1	0.20	0.35
b		0.45
D	9.00 BSC	
E	8.00 BSC	
e	0.80 BSC	

Array 8x6

**SG-BGA-6161 Drawing**

Status: Released

Scale: -

Rev: C

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